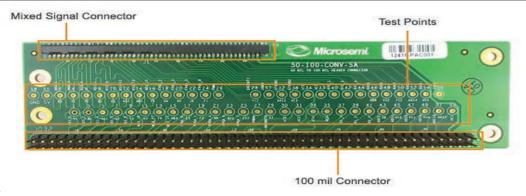


Mixed Signal Daughter Card Quickstart Card

Kit Contents - DMPM-DC-KIT

Quantity	Description			
1	50-100-CONV-SA mixed signal daughter card			
4	1/2" plastic standoffs			
4	Plastic screws (for 1/2' plastic standoffs)			



Overview

This daughter card is designed for connection to the mixed signal header on the SmartFusion® Evaluation Kit (A2F-EVAL-KIT-2) or Development Kit (A2F500-DEV-KIT-2). The board comes with rubber feet attached. If it is being used with the development kit, the standoffs supplied in the box can be attached to match board height.

Hardware Features

- Test points for signal probing
- Mixed signal header for daughter card support
- 100 mil header for wire-wrapped or soldered signals

Test Point (TP) Signals

TP	Signal	TP	Signal	TP	Signal	TP	Signal
TP1	MSS_GP_IO_0	TP16	MSS_GP_IO_15	TP31	AC2	TP46	ADC3
TP2	MSS_GP_IO_1	TP17	F2-200-IO_0	TP32	ATGND1	TP47	ADC6
TP3	MSS_GP_IO_2	TP18	F2-200-IO_2	TP33	AC3	TP48	ADC5
TP4	MSS_GP_IO_3	TP19	F2-200-IO_1	TP34	AT3	TP49	ADC8
TP5	MSS_GP_IO_4	TP20	F2-200-IO_3	TP35	AC4	TP50	ADC7
TP6	MSS_GP_IO_5	TP21	F2-200-IO_4	TP36	AT4	TP51	ADC10
TP7	MSS_GP_IO_6	TP22	F2-200-IO_5	TP37	AV1_1	TP52	ADC9

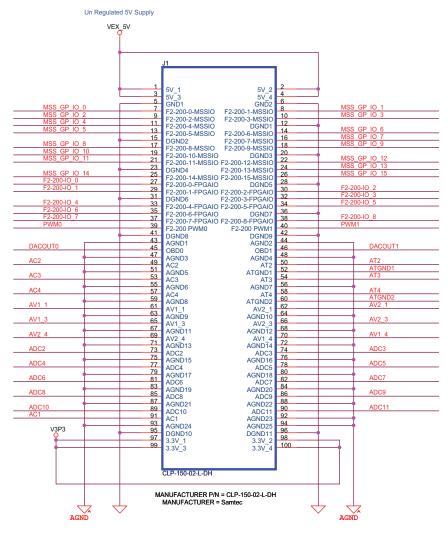
1



TP	Signal	TP	Signal	TP	Signal	TP	Signal
TP8	MSS_GP_IO_7	TP23	F2-200-IO_6	TP38	ATGND2	TP53	AC1
TP9	MSS_GP_IO_8	TP24	F2-200-IO_8	TP39	AV1_3	TP54	ADC11
TP10	MSS_GP_IO_9	TP25	F2-200-IO_7	TP40	AV2_1	TP55	VEX_5V
TP11	MSS_GP_IO_10	TP26	PWM1	TP41	AV2_4	TP56	V3P3
TP12	MSS_GP_IO_11	TP27	PWM0	TP42	AV2_3	TP57	GND
TP13	MSS_GP_IO_12	TP28	DACOUT1	TP43	ADC2	TP58	GND
TP14	MSS_GP_IO_13	TP29	DACOUT0	TP44	AV1_4		
TP15	MSS_GP_IO_14	TP30	AT2	TP45	ADC4		

The mixed signal connector connects directly to the SmartFusion Evaluation Kit or Development Kit mixed signal header.

Mixed Signal Connector

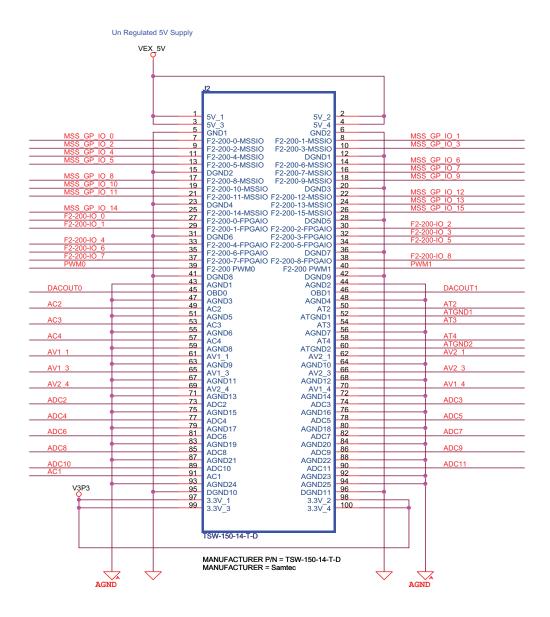


Matting connector " FTSH-150-01-L-D-RA"



This second connector can be used to probe signals or build add on connectors. It does not connect to any other Microsemi-specific hardware.

Break Out Board - Signal Connector





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Documentation Resources

For more information about the Mixed Signal Daughter Card, including user's guides, tutorials, and design examples, see the documentation at www.microsemi.com/products/fpga-soc/design-resources/dev-kits/smartfusion/mixed-signal-power-manager-4-0-mpm-daughter-card-kit#documents

Support

Technical support is available online at www.microsemi.com/soc/support and by email at soc tech@microsemi.com

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